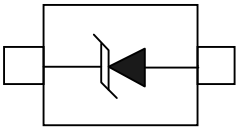
CESD3V3D3
Transient Voltage Suppression Diode

Features

360Watts peak pulse power (tp = 8/20μs)
Unidirectional configurations
Solid-state silicon-avalanche technology
Low clamping voltage
Low leakage current
IEC 61000-4-2 ±30kV contact ±30kV air
IEC 61000-4-4 (EFT) 40A (5/50ns)
IEC 61000-4-5 (Lightning) 30A (8/20μs)







SOD-323

Application

USB Vbus,
Power Line
Power management

Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power (t_p =8/20μs)	P_{PP}	360	Watts
Peak Pulse Current (t_p =8/20μs) (note1)	I_{pp}	30	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	30 30	kV
Lead Soldering Temperature	T_L	260(10seconds)	℃
Junction Temperature	T_J	-55 to + 150	℃
Storage Temperature	T_{stg}	-55 to + 150	℃

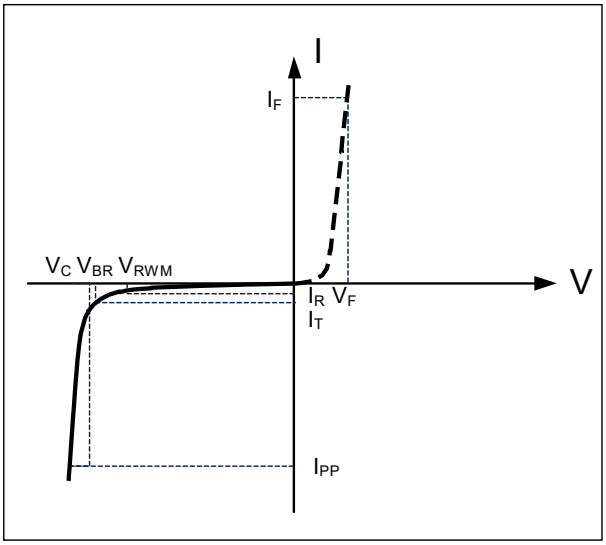
Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V_{RWM}				3.3	V
Reverse Breakdown Voltage	V_{BR}	I_T=1mA	5.0			V
Reverse Leakage Current	I_R	V_{RWM}=3.3V,T=25℃			1.0	uA
Clamping Voltage	V_C	I_{PP}=30A,t_p=8/20μs		10		V
Junction Capacitance	C_j	V_R = 0V, f = 1MHz		300		pF

Electronics Parameter

Symbol	Parameter
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Working Peak Reverse Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current

Note:. 8/20μs pulse waveform.



RATING AND CHARACTERISTIC CURVES

Figure 1: Peak Pulse Power vs. Pulse Time

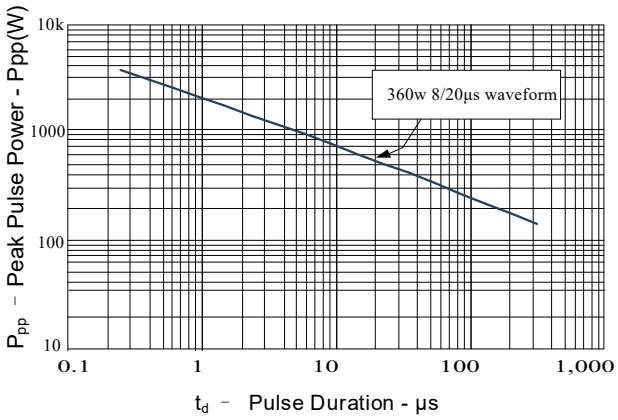


Figure 2: Power Derating Curve

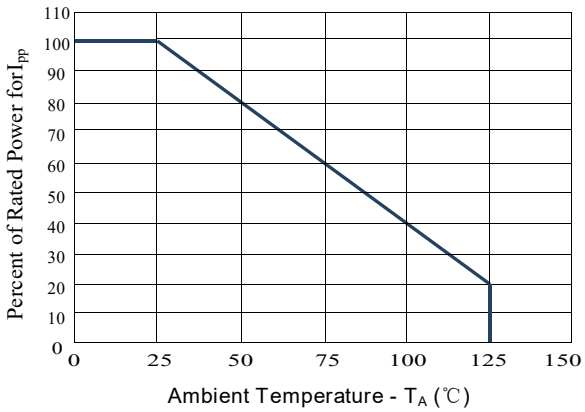


Figure3: Pulse Waveform

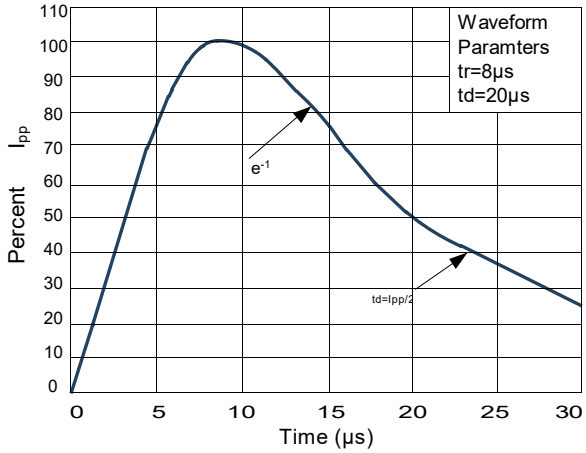
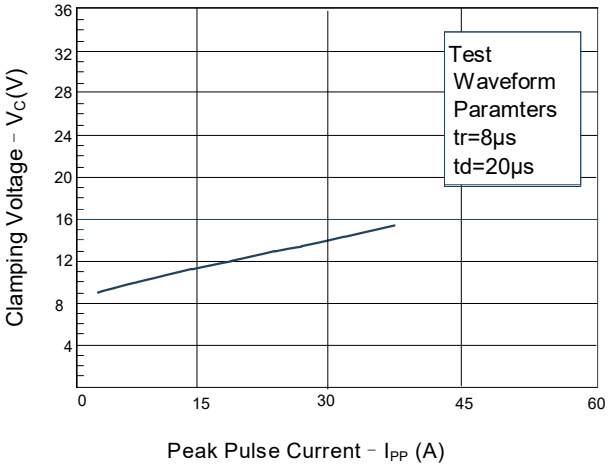


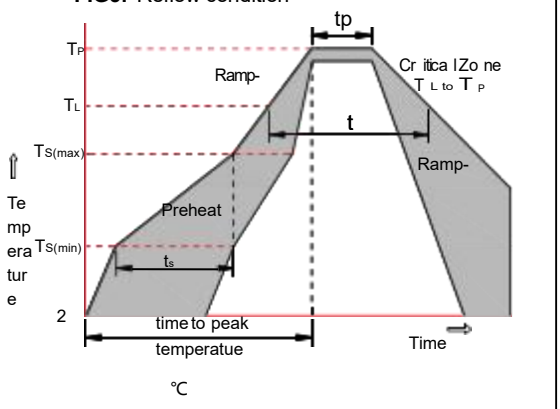
Figure 4: Clamping Voltage vs.Ipp



Soldering parameters

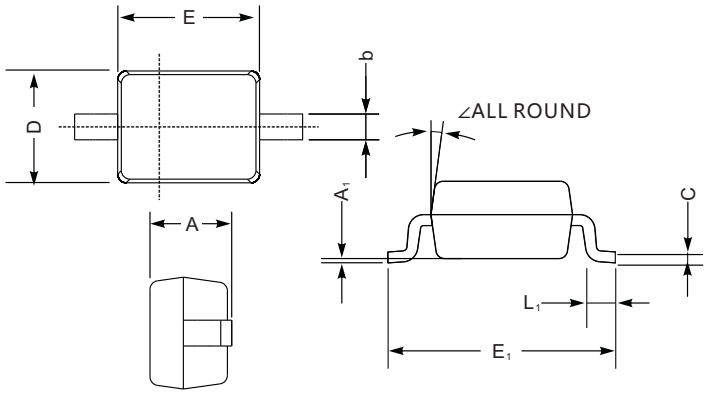
Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

FIG5: Reflow condition



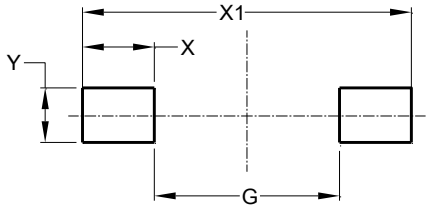
Package Dimensions & Suggested Pad Layout

SOD323



SOD-323 mechanical data

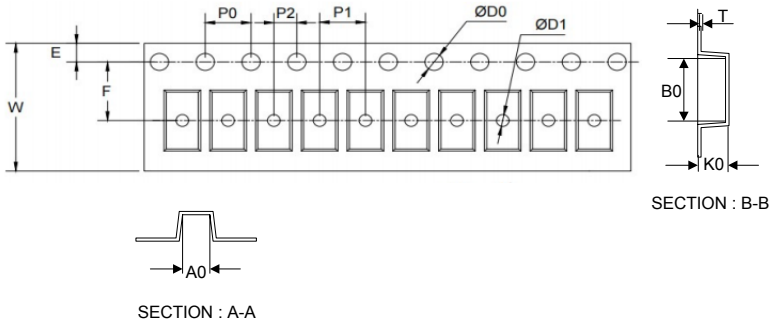
UNIT		A	C	D	E	E_1	b	L_1	A_1	∠
mm	max	1.1	0.15	1.4	1.8	2.75	0.4	0.45	0.2	9°
	min	0.8	0.08	1.2	1.4	2.55	0.25	0.2	—	
mil	max	43	5.9	55	70	108	16	16	8	
	min	32	3.1	47	63	100	9.8	7.9	—	



Dimensions	Value (in mm)
G	1.40
X	1.20
X1	3.80
Y	1.00

Tape & rell specification

Tape

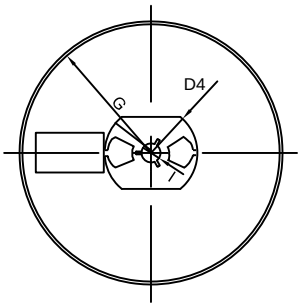


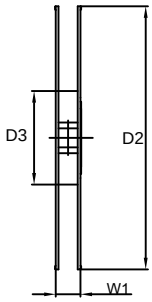
SECTION : B-B

SECTION : A-A

Symbol	Dimension (mm)
P0	4.00±0.20
P1	4.00±0.20
P2	2.00±0.20
D0	1.55±0.20
D1	1.00±0.20
E	1.55±0.25
F	3.60±0.20
W	8.00±0.20
A0	2.00±0.20
B0	3.25±0.20
K0	1.35±0.20
T	0.23±0.10

7” Reel





D2	177.0±5.0
D3	55Min.
D4	R24.6±2.0
G	R82.0±2.0
I	13.0±2.0
W1	10.20±3.0
Quantity: 3000PCS	